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NEC

NPN SILICON RF TWIN TRANSISTOR
μPA895TS

NPN SILICON RF TRANSISTOR (WITH 2 ELEMENTS) IN A 6-PIN SUPER LEAD-LESS MINIMOLD

FEATURES

- Built-in low voltage operation, low phase distortion transistor suited for OSC applications
  f_T = 4.5 GHz TYP., $|S_{21e}|^2$ = 4.0 dB TYP. @ V_{CE} = 1 V, I_C = 5 mA, f = 2 GHz
- Built-in 2 transistors (2 × 2SC5800)
- 6-pin super lead-less minimold package

BUILT-IN TRANSISTORS

	Q1, Q2
Flat-lead 3-pin thin-type ultra super minimold part No.	2SC5800

ORDERING INFORMATION

Part Number	Quantity	Supplying Form
μPA895TS	50 pcs (Non reel)	• 8 mm wide embossed taping
μPA895TS-T3	10 kpcs/reel	• Pin 1 (Q1 Collector), Pin 6 (Q1 Base) face the perforation side of the tape

Remark To order evaluation samples, contact your nearby sales office.
The unit sample quantity is 50 pcs.

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

Document No. PU10335EJ02V0DS (2nd edition)
Date Published September 2003 CP(K)
Printed in Japan

The mark ★ shows major revised points.

ABSOLUTE MAXIMUM RATINGS (T_A = +25°C)

Parameter	Symbol	Ratings	Unit
Collector to Base Voltage	V_{CBO}	9	V
Collector to Emitter Voltage	V_{CEO}	5.5	V
Emitter to Base Voltage	V_{EBO}	1.5	V
Collector Current	I_C	100	mA
Total Power Dissipation	P_{tot} Note	110 in 1 element	mW
		130 in 2 elements	
Junction Temperature	T_j	150	°C
Storage Temperature	T_{stg}	−65 to +150	°C

Note Mounted on 1.08 $cm^2 \times 1.0$ mm (t) glass epoxy PCB

ELECTRICAL CHARACTERISTICS (T_A = +25°C)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Collector Cut-off Current	I_{CBO}	V_{CB} = 5 V, I_E = 0 mA	–	–	600	nA
Emitter Cut-off Current	I_{EBO}	V_{EB} = 1 V, I_C = 0 mA	–	–	600	nA
DC Current Gain	h_{FE} Note 1	V_{CE} = 1 V, I_C = 5 mA	100	120	145	–
Gain Bandwidth Product (1)	f_T	V_{CE} = 1 V, I_C = 5 mA, f = 2 GHz	3.0	4.5	–	GHz
Gain Bandwidth Product (2)	f_T	V_{CE} = 1 V, I_C = 15 mA, f = 2 GHz	5.0	6.5	–	GHz
Insertion Power Gain (1)	$\lvert S_{21e} \rvert^2$	V_{CE} = 1 V, I_C = 5 mA, f = 2 GHz	3.0	4.0	–	dB
Insertion Power Gain (2)	$\lvert S_{21e} \rvert^2$	V_{CE} = 1 V, I_C = 15 mA, f = 2 GHz	4.5	5.5	–	dB
Noise Figure	NF	V_{CE} = 1 V, I_C = 10 mA, f = 2 GHz, $Z_S = Z_{opt}$	–	1.9	2.5	dB
Reverse Transfer Capacitance	C_{re} Note 2	V_{CB} = 0.5 V, I_E = 0 mA, f = 1 MHz	–	0.6	0.8	pF

Notes 1. Pulse measurement: PW ≤ 350 μs, Duty Cycle ≤ 2%

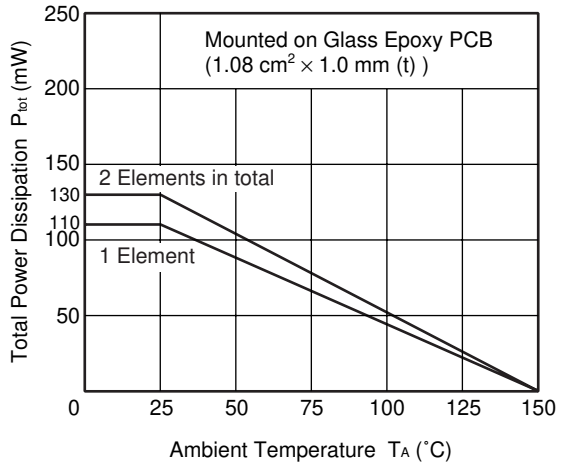
2. Collector to base capacitance when the emitter grounded

h_{FE} CLASSIFICATION

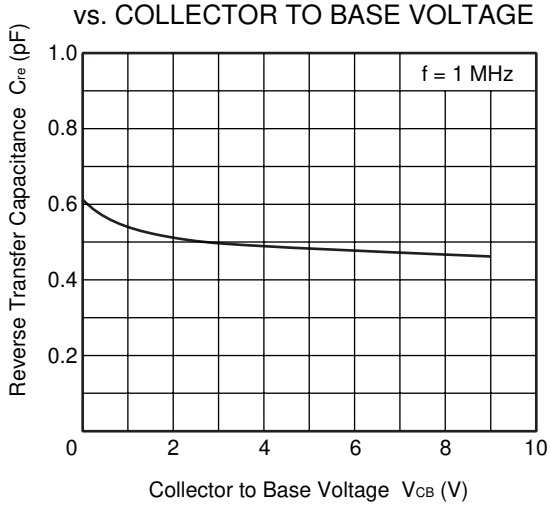
Rank	FB
Marking	kP
h_{FE} Value	100 to 145

★ TYPICAL CHARACTERISTICS (T_A = +25°C, unless otherwise specified)

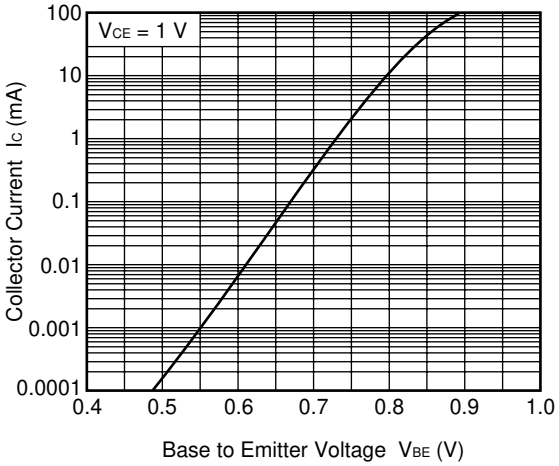
TOTAL POWER DISSIPATION vs. AMBIENT TEMPERATURE



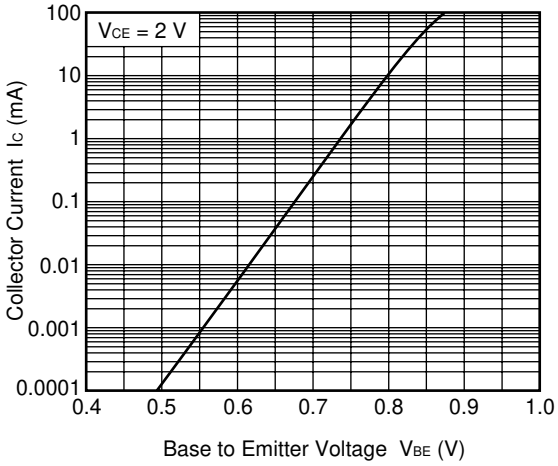
REVERSE TRANSFER CAPACITANCE vs. COLLECTOR TO BASE VOLTAGE



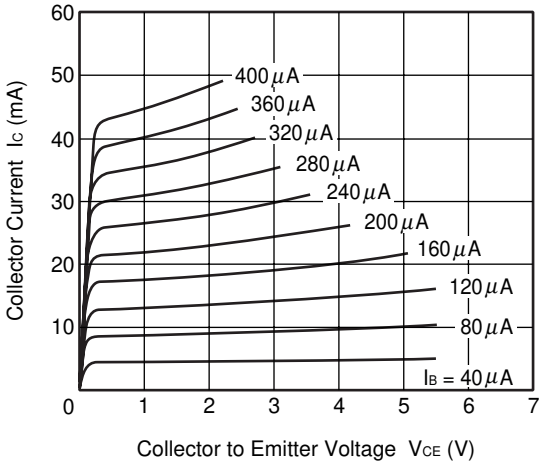
COLLECTOR CURRENT vs. BASE TO EMITTER VOLTAGE



COLLECTOR CURRENT vs. BASE TO EMITTER VOLTAGE

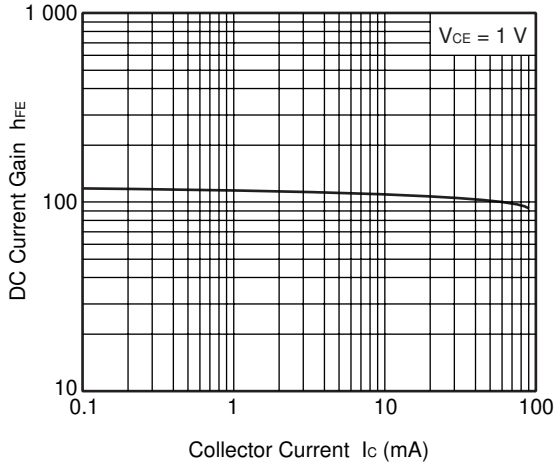


COLLECTOR CURRENT vs. COLLECTOR TO EMITTER VOLTAGE

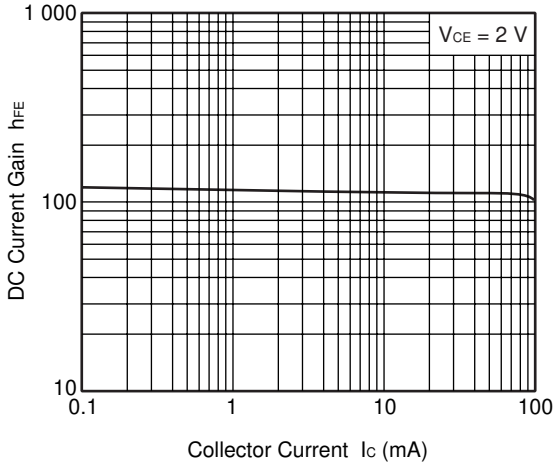


Remark The graphs indicate nominal characteristics.

DC CURRENT GAIN vs.
COLLECTOR CURRENT



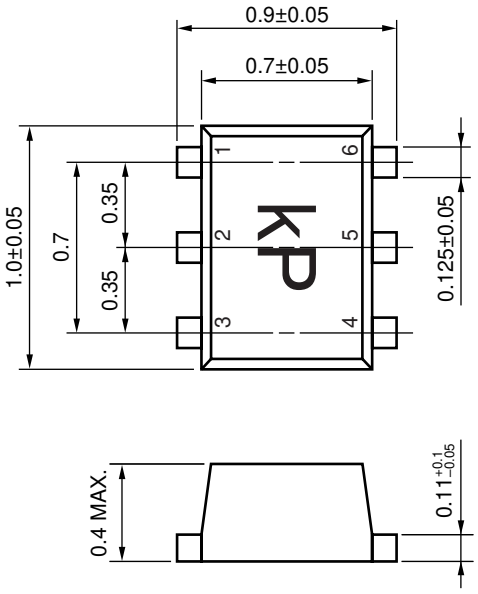
DC CURRENT GAIN vs.
COLLECTOR CURRENT



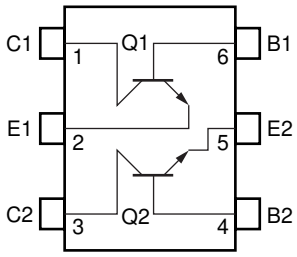
Remark The graphs indicate nominal characteristics.

PACKAGE DIMENSIONS

6-PIN SUPER LEAD-LESS MINIMOLD (UNIT: mm)



(Top View)



PIN CONNECTIONS

1. Collector (Q1)
2. Emitter (Q1)
3. Collector (Q2)
4. Base (Q2)
5. Emitter (Q2)
6. Base (Q1)

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